



SCIENTECH

# Sciencetech Corp(3583:TT)

M.T. Hsu 2025/03/18

# Safe Harbor Statement



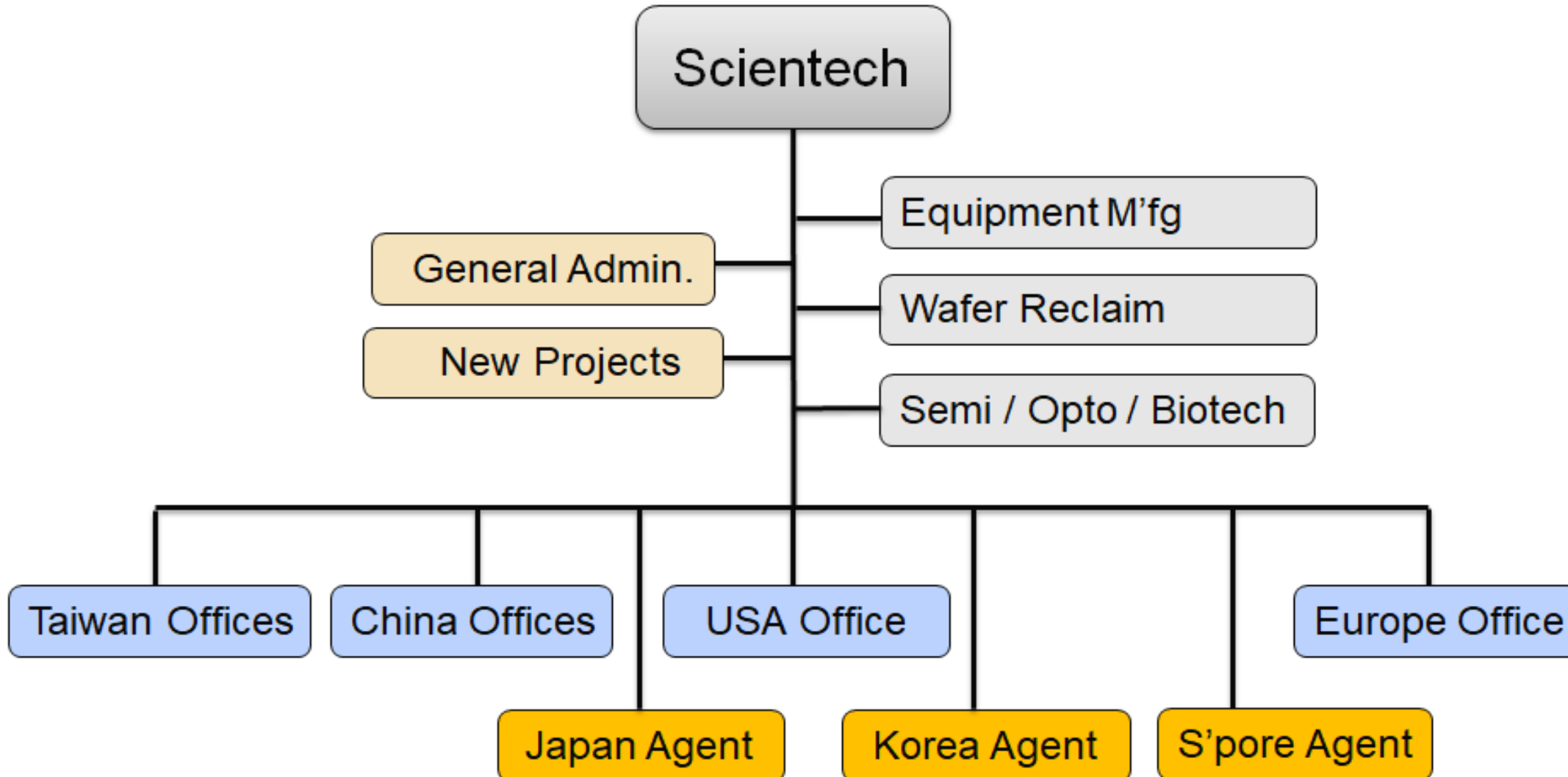
- **This Presentation contains certain forward-looking statements that are based on current expectations and are subject to known and unknown risks and uncertainties that could cause actual results to differ materially from those expressed or implied by such statements.**
- **Except as required by law, we undertake no obligation to update any forward –looking statements, whether as a result of new information, future events or otherwise.**

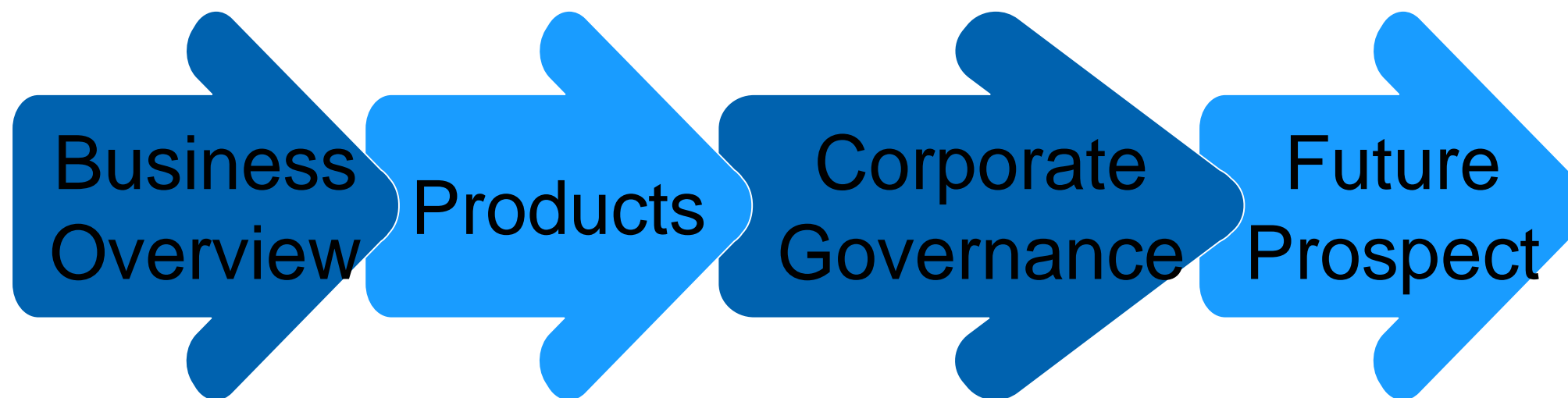
# Sciencetech Corp (3583:TT)



<b>Establishment</b>	1979/10/17
<b>Chairman</b>	H.L. Hsieh
<b>CEO</b>	M.T. Hsu
<b>Capital</b>	NT\$ 803 Million
<b>Revenue(2023)</b>	NT\$ 6,911 Million (Consolidated)
<b>No. Employees</b>	875 (Consolidated)
<b>Location</b>	Taiwan : Taipei, Hukou , Hsinchu, Tainan, Kaohsiung Subsidiary Company : China(17 cities including Shanghai) , HK,USA , Europe(Austria) Business Support : Japan,Singapore,South Korea
<b>Products</b>	Equipment Manufacturing 、 Wafer Reclaim 、 Trading(Agent/Distributor)

# Organization





# Business Overview

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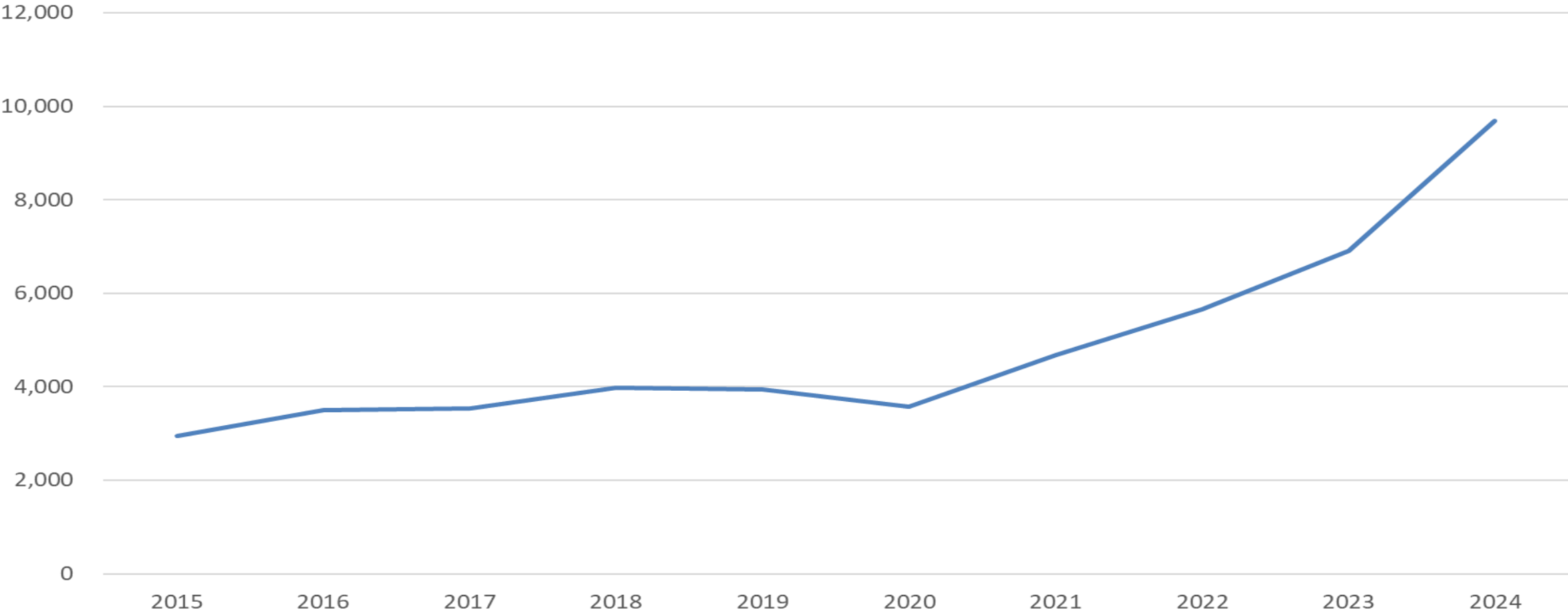
# Income Statement

Units : NT \$ M	2020	2021	2022	2023	2024
Revenues	3,580	4,684	5,650	6,911	9,688
Gross Profit	1,456	1,667	2,084	2,201	2,906
Operating Expenses	991	1,112	1,374	1,483	1,790
Operating Income	465	555	710	718	1116
Income Before Tax	389	524	736	860	1277
Net Income	305	420	568	650	927
EPS	<b>3.80</b>	<b>5.23</b>	<b>7.08</b>	<b>8.10</b>	<b><u>11.54</u></b>
Gross Margin	41%	36%	37%	32%	30%
Operating Margin	13%	12%	13%	10%	12%
Income Before Tax Margin	11%	11%	13%	12%	13%

# Revenue



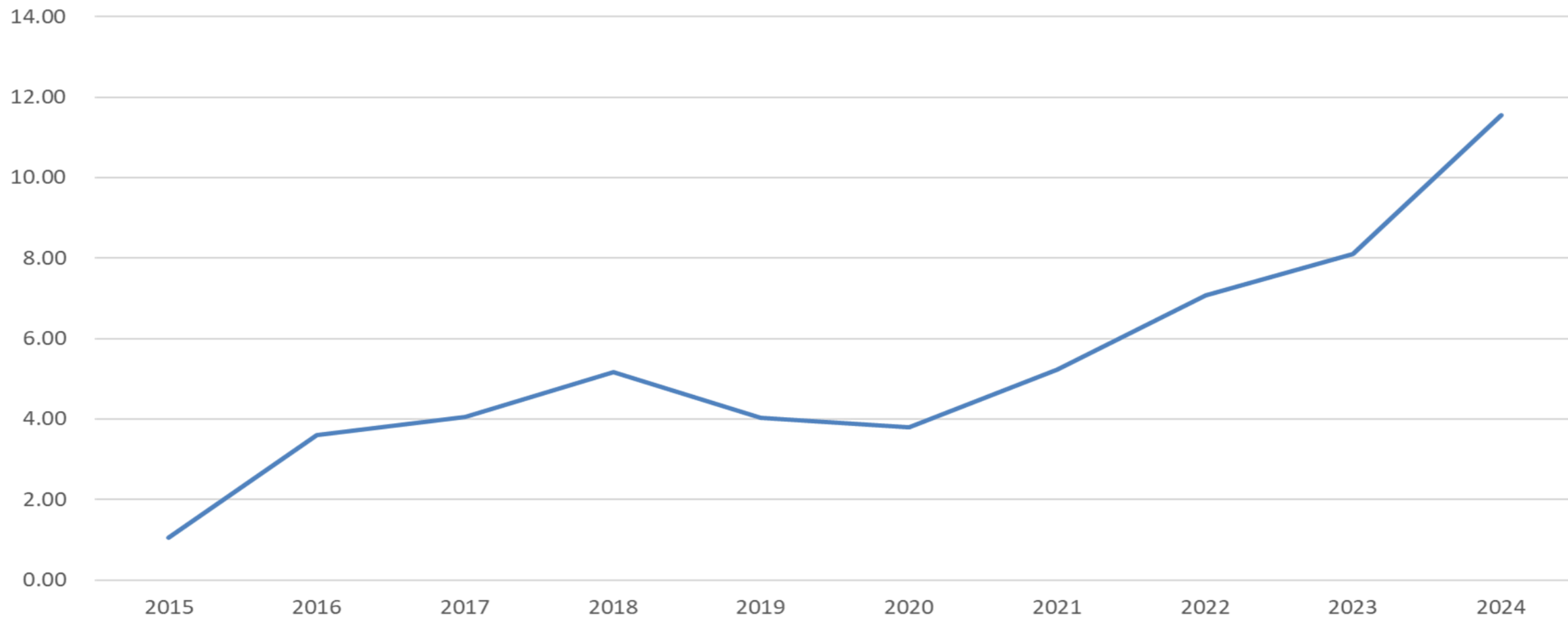
Units NT \$ M	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024
Revenue	2,942	3,495	3,539	3,988	3,949	3,580	4,684	5,650	6,911	9,688





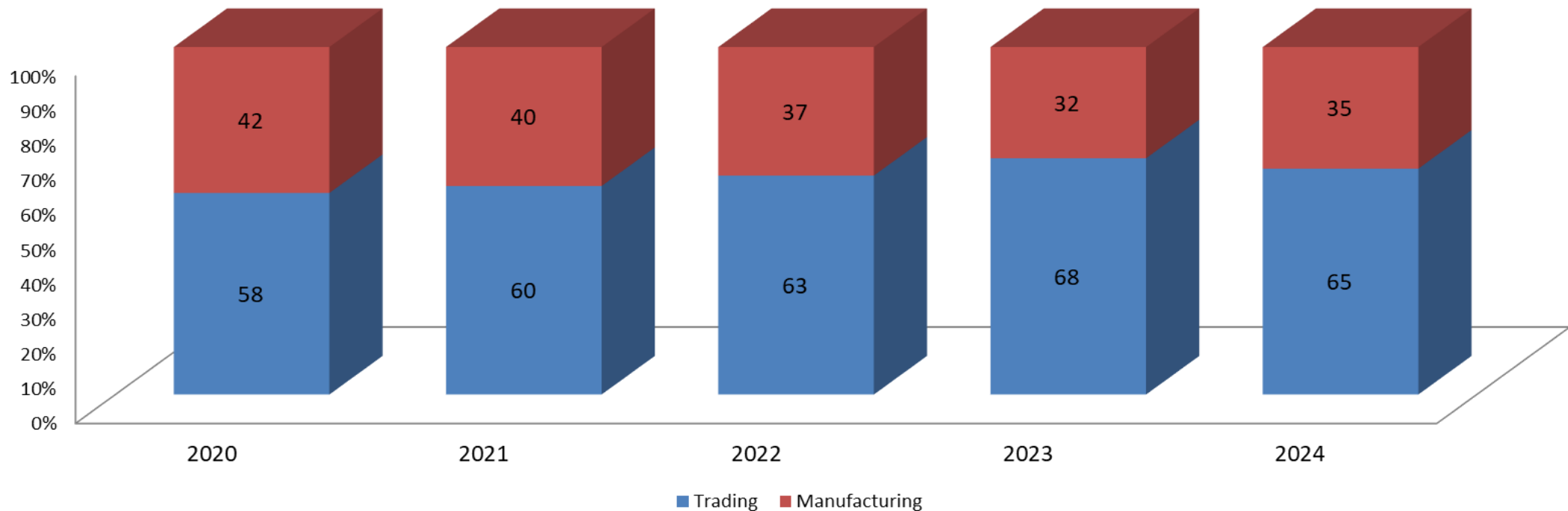
# EPS

	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024
EPS	1.06	3.60	4.05	5.16	4.02	3.8	5.23	7.08	8.10	11.54



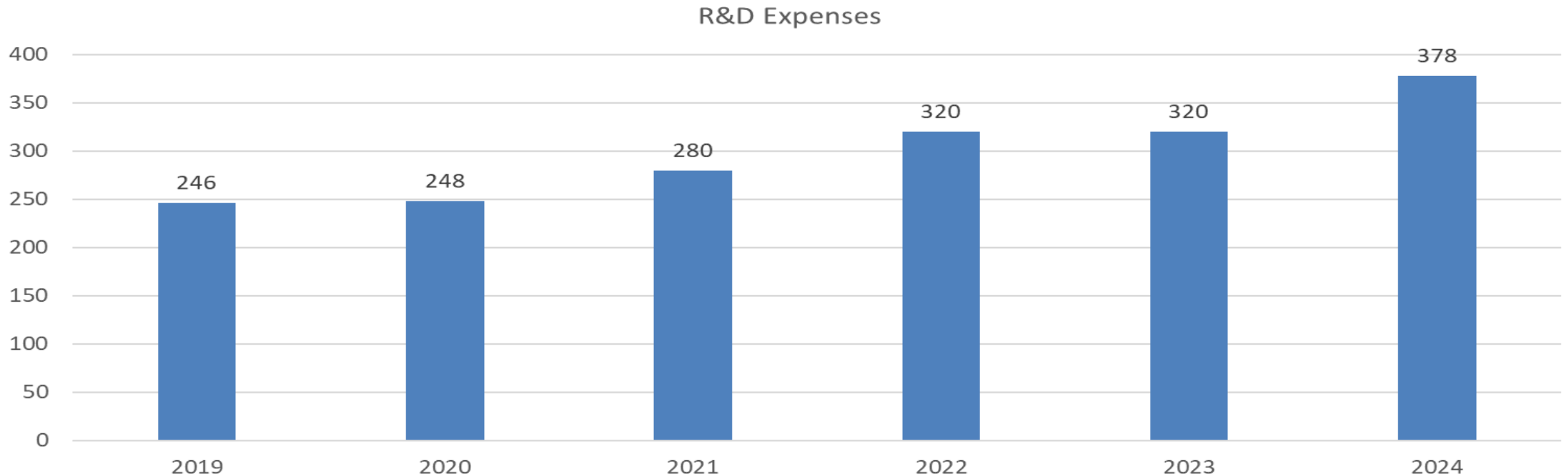
# Products Mix

Units : %	2020	2021	2022	2023	2024	Gross Margin
Trading	58	60	63	68	67	Below Average
Manufacturing	42	40	37	32	33	Above Average



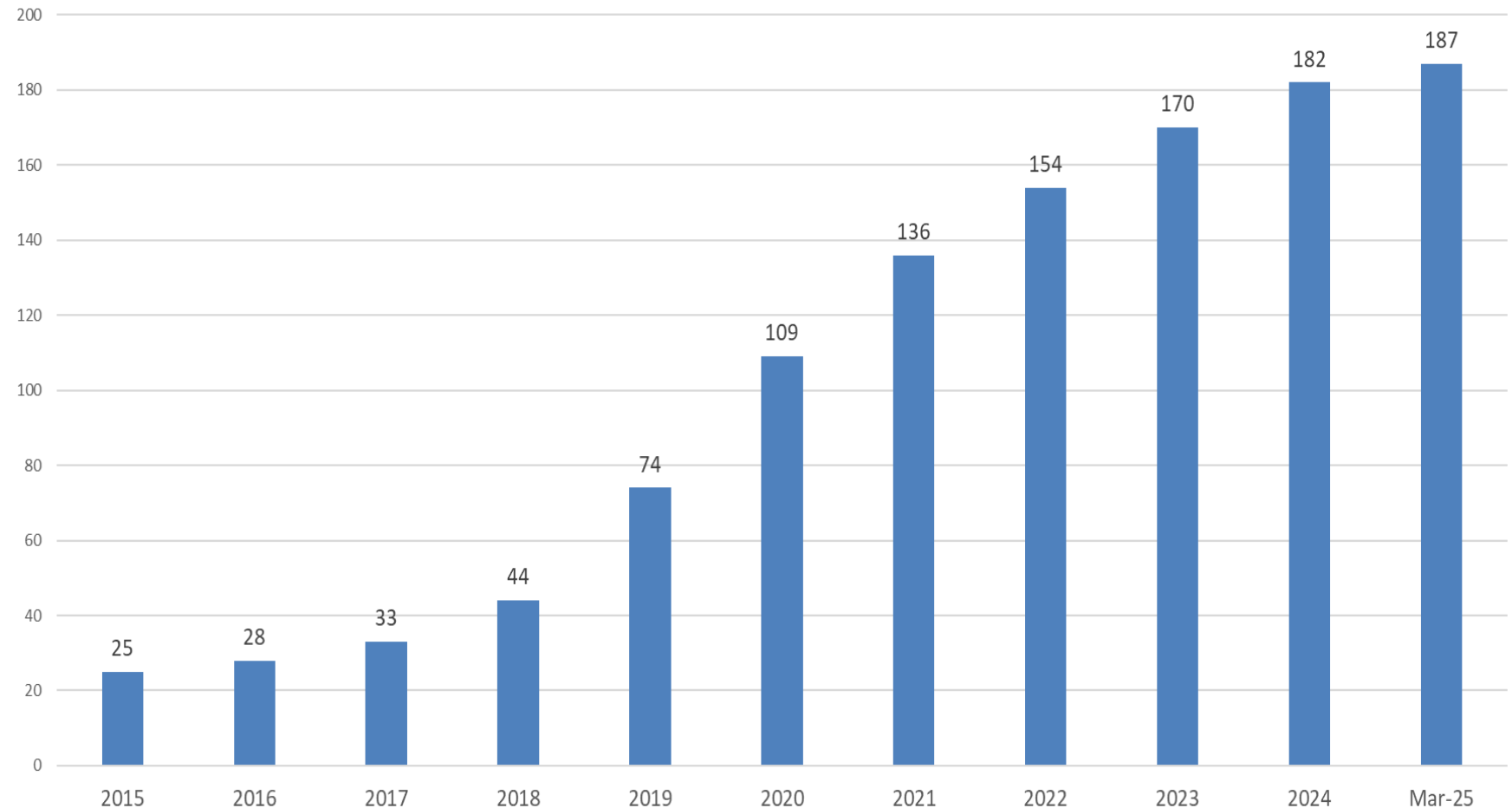
# R&D Expenses

Units NT \$ M	2019	2020	2021	2022	2023	2024
R&D Expenses	246	248	280	320	341	378
Expenses as % of Revenue	6.2%	6.9%	6.0%	5.7%	4.9%	3.9%
<b>Expenses as % of Manufacturing</b>	<b>15.2%</b>	<b>16.5%</b>	<b>14.9%</b>	<b>15.3%</b>	<b>15.7%</b>	<b>11.3%</b>



# R&D Patents Number

- The cumulative number of patents on file is 187, and 40 applications are pending.



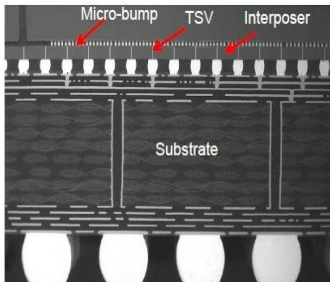
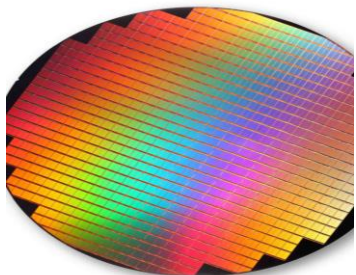
# Products

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# What We Do

- **Industries which we serve :**
  - **Semiconductor (Front-End and Advanced Packaging)**
  - **Compound Semiconductor**
  - **LED / Mini LED / Micro LED**
  - **Flat Panel Display**
  - **Solar Cell / Battery**
  - **Biotech / Chemistry Analysis / Scientific Instrument,...**



# Product and Technology

- Semiconductor
- Compound SEMI
- LED / Micro LED
- Flat Panel Display
- Solar Cell / Battery
- Biotech
- Scientific Inst.

**Equipment  
Design  
M'fg**

- Wet-Process Tools
- Wafer Temporary Bonding  
Debonding System
- SEMI / Compound / LED

**Representative  
/ Distributor**

**Wafer Reclaim  
Service**

- 12" Si Wafer
- 6" SiC Wafer



# Wafer Reclaim Service

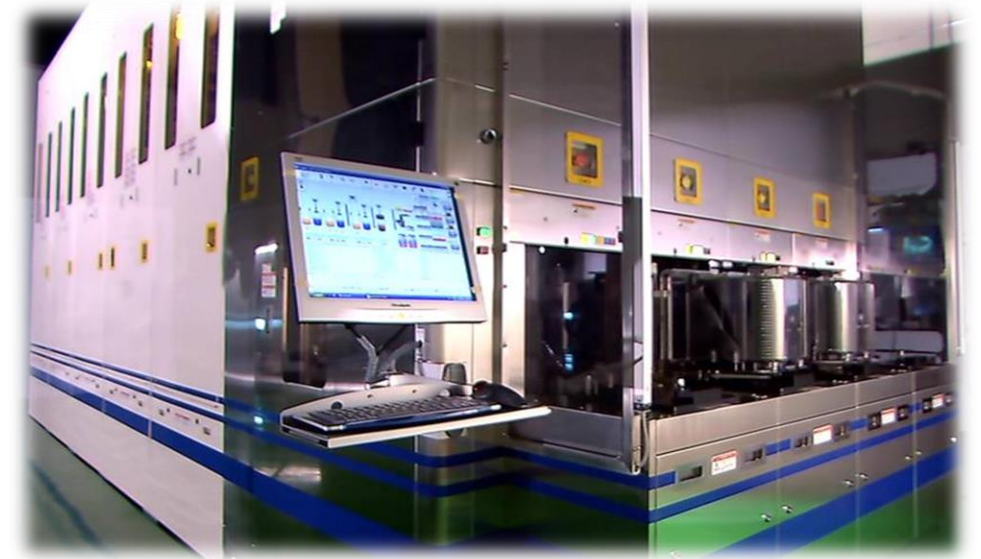
- **12" Wafer Reclaim**
  - Capacity: 160K/Month
  - Cu and Non-Cu Process
- **SiC Post Slicing Process and Reclaim**
  - Capacity: 800片/Month





# Wet Process Equipment

- **Wet-Bench / Single-Wafer Wet Process Equipment**
- **Applications :**
  - Advanced Packaging Process
  - Semiconductor Front-End Process
  - Compound Semiconductor
  - Microelectromechanical Systems (MEMS)
  - High-End LED Fully-Automatic Advanced Process

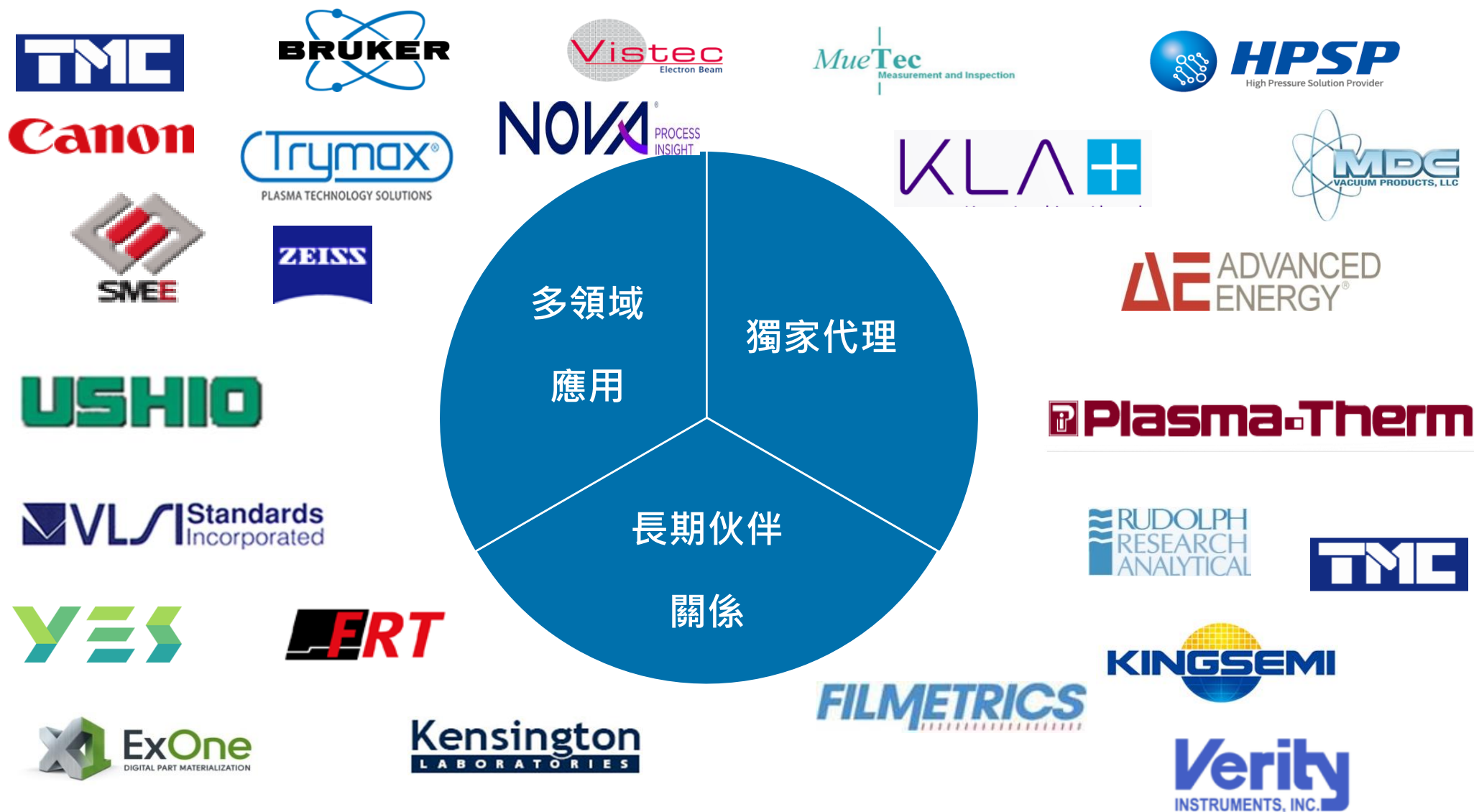


# Temporary Bonding Debonding System

- **Temporary Bonding Debonding System (TBDB)**
- **Application: IGBT Power Device, Advanced Packaging for Semiconductor and LED**
  - Temporary Bonding System
  - Temporary Debonding System
  - Release Layer Formation System
  - Carrier (Glass) Recycling System



# Trading(Agent/Distributor)



# Corporate Governance

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# ISO Certifications

Initial Certification  
2014/5/27  
Valid Date :  
2020/5/28 ~ 2023/5/27



Issue 4. Certified since  
2010/3/24  
Valid Date :  
2019/4/30 ~ 2022/4/30



Issue 3. Certified since  
2019/4/30  
Valid Date :  
2019/4/30 ~ 2022/4/30



Issue 1. Certified since  
2019/11/20  
Valid Date :  
2019/11/20 ~ 2022/11/19



Issue 1. Certified since  
2021/09/29  
Valid Date :  
2021/09/29 ~ 2024/09/28



ISO9001

ISO14001

ISO45001

ISO27001  
資訊安全

ISO22301  
營運持續

## • TIPS-AA級驗證



Taiwan Intellectual Property Management System

### 台灣智慧財產管理規範 (TIPS) 驗證登錄證書

Certificate of Taiwan Intellectual Property Management System

貴公司所建置之智慧財產管理制度，通過台灣智慧財產管理規範 (TIPS) 推行體系之驗證，特此證明。相關登錄事項如下：

- 一、公司名稱：卓新企業股份有限公司
- 二、受評部門：全公司
- 三、受評地址：新竹縣港口鄉中華路 16 號
- 四、證書編號：TIPS-2019-驗證-008
- 五、有效期限：2021/12/31
- 六、管理標的：☒專利 ☒商標 ☐著作權 ☐營業秘密 ☐積體電路佈局
- 排除適用：無
- 七、驗證類別：☒AA 級 ☐A 級 (2016 年版)

經濟部工業局  
局長 呂正華

### Certificate of Compliance

This is to certify that the Intellectual Property Management System of the following organization has been verified and fulfilled the requirements of TIPS.

- 1. Company Name : Scientech Corporation
- 2. Registered Department : All Company
- 3. Registered Address : No. 16, Jhonghua Rd., Hukou Township, Hsinchu County 30352, Taiwan (R.O.C.)
- 4. Number of Registration : TIPS-2019-cert-008
- 5. Date of Expiration : December 31, 2021
- 6. Items : ☒ Patent ☒ Trademark ☐ Copyright ☐ Trade Secret ☐ Integrated Circuit Layout
- Exclusion : None
- 7. Certification Level : ☒ AA ☐ A (2016)

Director General  
Industrial Development Bureau, MOEA 

# ESG Sustainable development

**Sustainability report officially released on Aug,2024**



E



**Environmentally friendly**

S



**Warm workplace**



**Give back to society**

G



**Corporate Governance**



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Thank You!

<https://www.scientech.com.tw>